

## PATENT APPLICATION

DECLARATION AND POWER OF ATTORNEY  
FOR PATENT APPLICATIONATTORNEY DOCKET NO. 70030259

As a bel w named inventor, I hereby declare that:

My residence/post office address and citizenship are as stated below next to my name;

I believe I am the riginal, first and sole inv ntor (if only ne name is listed bel w) r an riginal, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and f r which a patent is sought on the inventi n entitled:

**PACKAGING DEVICE FOR SEMICONDUCTOR DIE, AND SEMICONDUCTOR DEVICE INCORPORATING SAME**

th specification of which is attached hereto unless the following box is checked:

( ) was filed on \_\_\_\_\_ as US Application Serial No. or PCT International Application Number \_\_\_\_\_ and was amended on \_\_\_\_\_ (if applicable).

I hereby state that I have reviewed and understood the contents of the above-identified specification, including the claims, as amended by any amendment(s) referred to above. I acknowledge the duty to disclose all information which is material to patentability as defined in 37 CFR 1.56.

## Foreign Application(s) and/or Claim of Foreign Priority

I hereby claim foreign priority benefits under Title 35, United States Code Section 119 of any foreign application(s) for patent or inventor(s) certificate listed below and have also identified below any foreign application for patent or inventor(s) certificate having a filing date before that of the application on which priority is claimed:

COUNTRY	APPLICATION NUMBER	DATE FILED	PRIORITY CLAIMED UNDER 35 U.S.C. 119
			YES: _____ NO: _____
			YES: _____ NO: _____

## Provisional Application

I hereby claim the benefit under Title 35, United States Code Section 119(e) of any United States provisional application(s) listed below:

APPLICATION SERIAL NUMBER	FILING DATE

## U. S. Priority Claim

I hereby claim the benefit under Title 35, United States Code, Section 120 of any United States application(s) listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of Title 35, United States Code Section 112, I acknowledge the duty to disclose material information as defined in Title 37, Code of Federal Regulations, Section 1.56(a) which occurred between the filing date of the prior application and the national or PCT international filing date of this application:

APPLICATION SERIAL NUMBER	FILING DATE	STATUS (patented/pending/abandoned)

## POWER OF ATTORNEY:

As a named inventor, I hereby appoint the following attorney(s) and/or agent(s) to prosecute this application and transact all business in the Patent and Trademark Office connected therewith:

Customer Number 022678Place Customer  
Number Bar Code  
Label here

Send Correspondence to:  
**AGILENT TECHNOLOGIES, INC.**  
 Legal Department, DL429  
 Intellectual Property Administration  
 P. . Box 7599  
 Loveland, Colorado 80537-0599

Direct Telephone Calls To:

Ian Hardcastle  
 (650) 485-3018

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that wilful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such wilful false statements may jeopardize the validity of the application or any patent issued thereon.

Full Name of Inventor: Kong Wang LeeCitizenship: MalaysianResidence: Lahat Court 48-2-1 Jalan Sekolah La Sall , 10450 Penang, MalaysiaPost Office Address: Same as ResidenceInventor's Signature: 

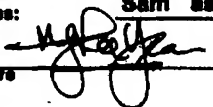
Date

26 June 2003

Rev 01/02 (DecPwr)

Use Page Two For Additional Inventor(s) Signature(s)

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**DECLARATION AND POWER OF ATTORNEY  
FOR PATENT APPLICATION (continued)**ATTORNEY DOCKET NO. **70030259**Full Name of # 2 Joint Inventor: Kee Yean Ng Citizenship: MalaysianResidence: 6, Halaman Kikik, Taman Inderawasih, 13600 Prai, Penang, MalaysiaPost Office Address: Same as ResidenceInventor's Signature: Date: June 26, 2003Full Name of # 3 Joint Inventor: Yew Cheong Kuan Citizenship: MalaysianResidence: 8-4-5 Desa University, Jalan Sungai Dua, 11700 Penang, MalaysiaPost Office Address: Same as ResidenceInventor's Signature: Date: June 26, 2003Full Name of # 4 Joint Inventor: Gin Ghee Tan Citizenship: MalaysianResidence: 18-11-03, Taman Seri Sari, Hilir Payar Terubong 1, Relau, 11900Post Office Address: Same as Residence Bayan Lepas, Penang, MalaysiaInventor's Signature: Date: June 26, 2003Full Name of # 5 Joint Inventor: Cheng Why Tan Citizenship: MalaysianResidence: 3843, Chip Joo Estate, Bukit Tengah, 14000, Bukit Mertajam,Post Office Address: Same as Residence Penang, MalaysiaInventor's Signature: Date: June 26, 2003

Full Name of # 6 Joint Inventor: \_\_\_\_\_ Citizenship: \_\_\_\_\_

Residence: \_\_\_\_\_

Post Office Address: \_\_\_\_\_

Inventor's Signature: \_\_\_\_\_ Date: \_\_\_\_\_

Full Name of # 7 Joint Inventor: \_\_\_\_\_ Citizenship: \_\_\_\_\_

Residence: \_\_\_\_\_

Post Office Address: \_\_\_\_\_

Inventor's Signature: \_\_\_\_\_ Date: \_\_\_\_\_

Full Name of # 8 Joint Inventor: \_\_\_\_\_ Citizenship: \_\_\_\_\_

Residence: \_\_\_\_\_

Post Office Address: \_\_\_\_\_

Inventor's Signature: \_\_\_\_\_ Date: \_\_\_\_\_